

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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Email & Skype: info@chipsmall.com Web: www.chipsmall.com

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MI0805M221R-10

UNCONTROLLED **DOCUMENT**

PHYSICAL DIMENSIONS:

0amp 500ma

1000ma

- 1500ma

2000ma

2500ma

300

250

200

150

100

50

MPEDANCE

A 2.00 [.079] ± 0.20 [.008]

1.25 [.049] ± 0.20 [.008]

± 0.20 [.008] C 0.90 [.035]

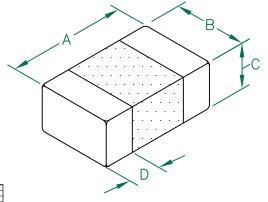
D 0.51 [.020] ± 0.25 [.010]

Z vs. FREQUENCY

IMPEDANCE UNDER DC BIAS

FREQUENCY (MHz)

|Z| , R, AND XL vs. FREQUENCY





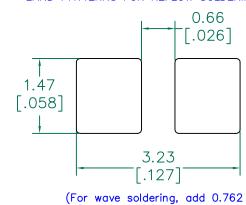
ELECT	ELECTRICAL CHARACTERISTICS:												
Z @ 100N (Ω)	1Hz	DCR (Ω)	Rated Current										
Nominal	220												
Minimum	165												
Maximum	275	0.05	2500 mA										

NOTES: UNLESS OTHERWISE SPECIFIED

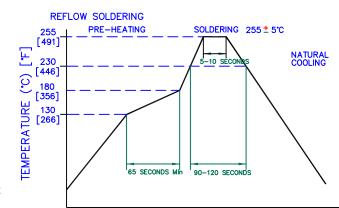
- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL, PAPER TAPE.
- 2. TERMINATION FINISH IS 100% TIN.
- 3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 4. OPERATING TEMP. RANGE: -40°C~+125°C. (INCLUDING SELF-HEATING)

LAND PATTERNS FOR REFLOW SOLDERING

RECOMMENDED SOLDERING CONDITIONS



[.030] to this dimension)



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D	ADD OPERATING TEMPERATURE	08/05/13	QU	PROJECT/PART NUMBER:	Т	REV	PART TY	PE:	DRAWN BY:	
U	UPDATE LAIRD LOGO AND REFLOW CURVE	00/00/10	ď	MI0805M221R-10	١I	D	CO-FIRE		ТМВ	
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AGILENT E4991A RF Impedance/Material Analyzer HP 16092A Test Fixture. TEST REF. 3124